

## Product Summary

<b>BV<sub>DSS</sub></b>	<b>R<sub>DSON</sub> max</b>	<b>I<sub>D</sub> max</b> <b>T<sub>C</sub> = +25°C</b>
<b>-20V</b>	32mΩ @ V <sub>GS</sub> = -4.5V	-13A
	53mΩ @ V <sub>GS</sub> = -2.5V	-10A

## Description and Applications

This MOSFET is designed to minimize the on-state resistance (R<sub>DSON</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery Management Application
- Power Management Functions
- DC-DC Converters

## Features and Benefits

- 0.6mm Profile – Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Low On-Resistance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

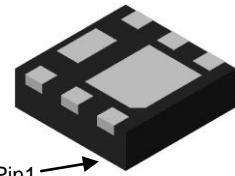
## Mechanical Data

- Case: U-DFN2020-6 (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.0065 grams (Approximate)

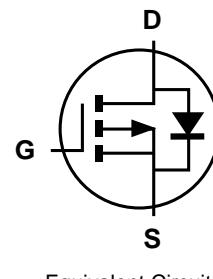
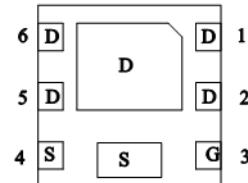
U-DFN2020-6 (Type F)



Top View



Bottom View



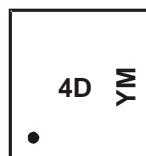
## Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2040UFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMP2040UFDF-13	U-DFN2020-6 (Type F)	10,000/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



4D = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: D = 2016)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2016	2017	2018	2019	2020	2021	2022	2023				
Code	D	E	F	G	H	I	J	K				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			$V_{DSS}$	-20	V
Gate-Source Voltage			$V_{GSS}$	$\pm 12$	V
Continuous Drain Current (Note 6) $V_{GS} = -4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	-6.1 -4.9	A
Continuous Drain Current (Note 7) $V_{GS} = -4.5\text{V}$	Steady State	$T_C = +25^\circ\text{C}$ $T_C = +70^\circ\text{C}$	$I_D$	-13 -10	A
Pulsed Drain Current (10 $\mu\text{s}$ pulse, duty cycle = 1%)			$I_{DM}$	-35	A
Continuous Source-Drain Diode Current (Note 6)			$I_S$	-2.0	A
Avalanche Current (Note 8) $L = 0.1\text{mH}$			$I_{AS}$	-17	A
Avalanche Energy (Note 8) $L = 0.1\text{mH}$			$E_{AS}$	14	mJ

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	$P_D$	0.8	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	149	°C/W
	$t < 10\text{s}$		95	
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	$P_D$	1.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	70	°C/W
	$t < 10\text{s}$		45	
Thermal Resistance, Junction to Case (Note 7)	Steady State	$R_{\theta JC}$	16	°C/W
Operating and Storage Temperature Range	$T_J, T_{STG}$		-55 to +150	°C

**Electrical Characteristics** ( $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 9)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-20	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	—	—	-1	$\mu\text{A}$	$V_{DS} = -16\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 9)</b>						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	-0.6	—	-1.5	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	22	32	$\text{m}\Omega$	$V_{GS} = -4.5\text{V}, I_D = -8.9\text{A}$
		—	31	53		$V_{GS} = -2.5\text{V}, I_D = -6.9\text{A}$
Diode Forward Voltage	$V_{SD}$	—	-0.7	-1.2	V	$V_{GS} = 0\text{V}, I_S = -2.9\text{A}$
<b>DYNAMIC CHARACTERISTICS (Note 10)</b>						
Input Capacitance	$C_{iss}$	—	834	—	$\text{pF}$	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	—	133	—		
Reverse Transfer Capacitance	$C_{rss}$	—	105	—		
Gate Resistance	$R_G$	—	4.9	—	$\Omega$	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Total Gate Charge ( $V_{GS} = -4.5\text{V}$ )	$Q_g$	—	8.6	—	$\text{nC}$	$V_{DS} = -6\text{V}, I_D = -8.9\text{A}$
Total Gate Charge ( $V_{GS} = -8\text{V}$ )	$Q_g$	—	19	—		
Gate-Source Charge	$Q_{gs}$	—	1.5	—		
Gate-Drain Charge	$Q_{gd}$	—	2.5	—	$\text{ns}$	$V_{DD} = -6\text{V}, R_L = 6\Omega$ $V_{GS} = -4.5\text{V}, R_G = 6\Omega, I_D = -1\text{A}$
Turn-On Delay Time	$t_{D(\text{ON})}$	—	5.8	—		
Turn-On Rise Time	$t_R$	—	7.7	—		
Turn-Off Delay Time	$t_{D(\text{OFF})}$	—	28.1	—		
Turn-Off Fall Time	$t_F$	—	14.6	—		
Body Diode Reverse Recovery Time	$t_{RR}$	—	9.8	—	$\text{ns}$	$I_F = -8.9\text{A}, di/dt = -100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	$Q_{RR}$	—	2.7	—	$\text{nC}$	$I_F = -8.9\text{A}, di/dt = -100\text{A}/\mu\text{s}$

Notes:

5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).
8.  $I_{AS}$  and  $E_{AS}$  rating are based on low frequency and duty cycles to keep  $T_J = +25^\circ\text{C}$ .
9. Short duration pulse test used to minimize self-heating effect.
10. Guaranteed by design. Not subject to product testing.

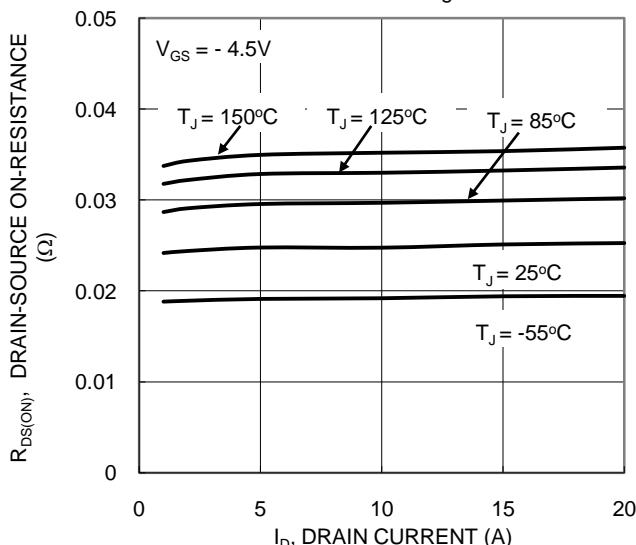
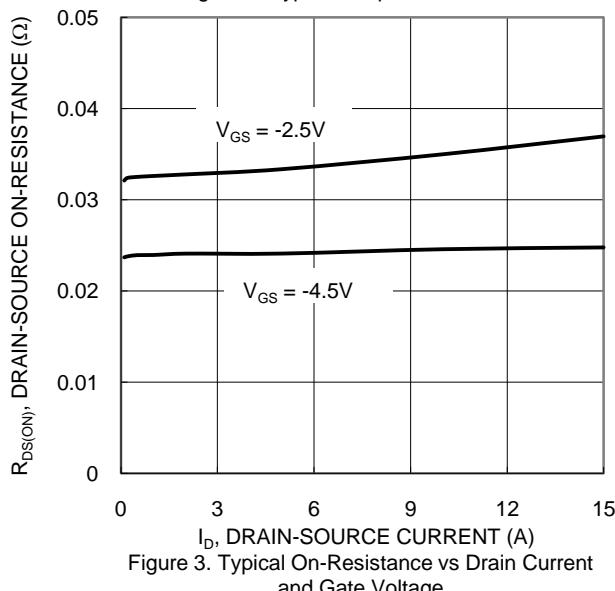
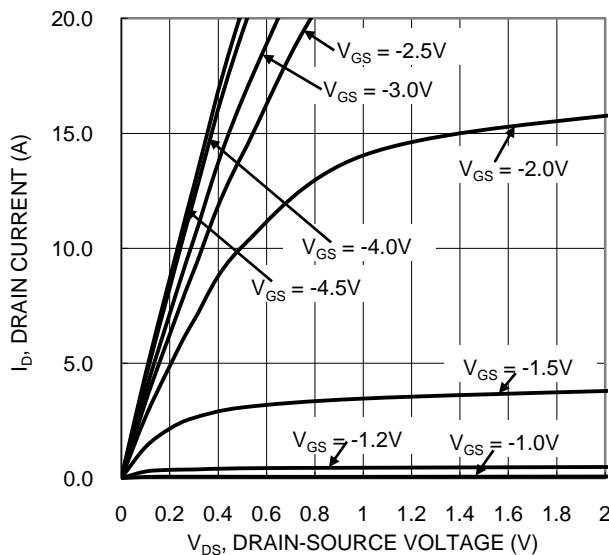
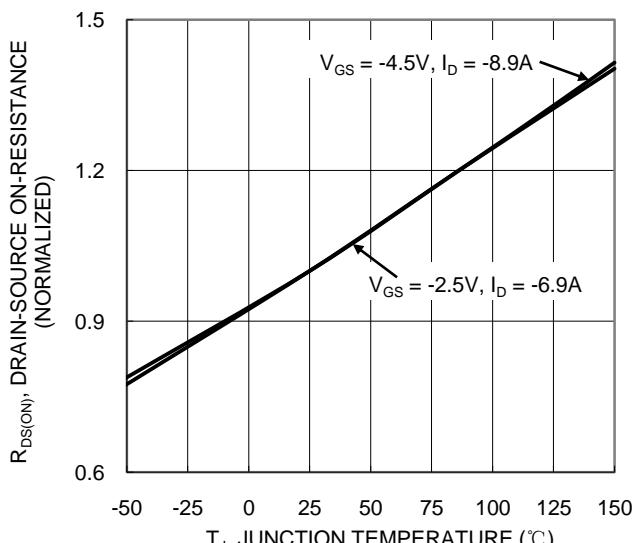
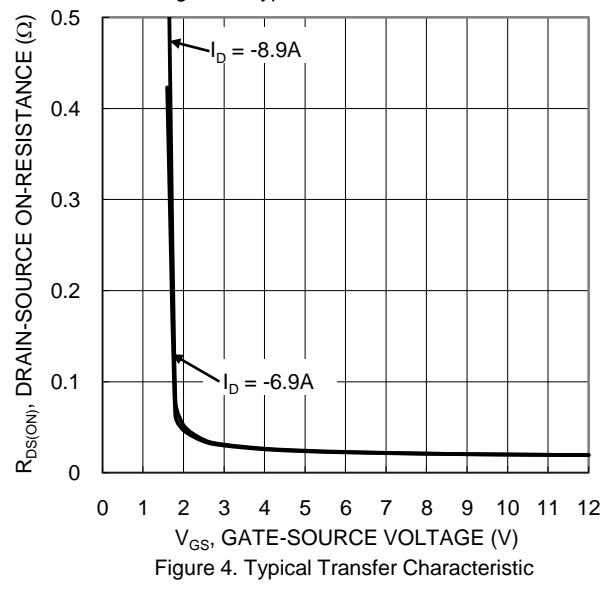
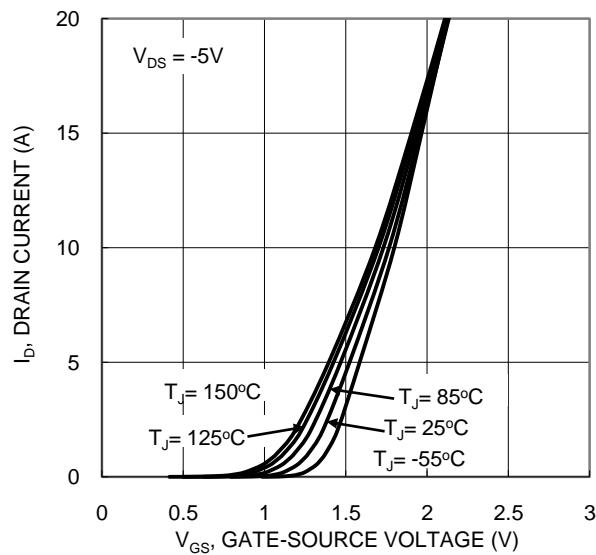
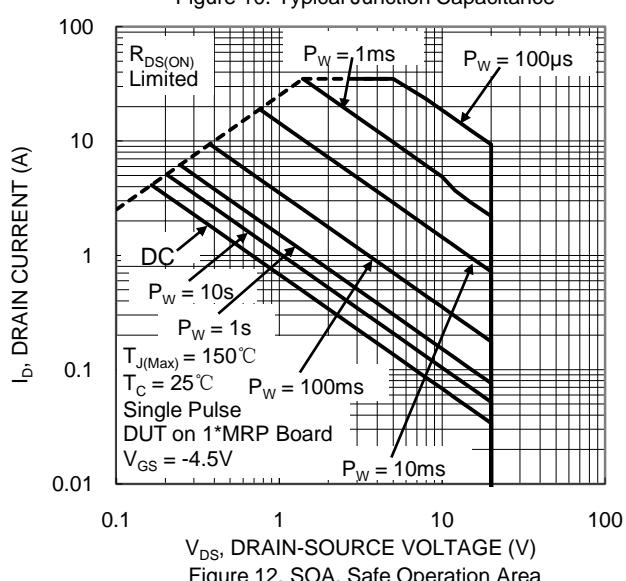
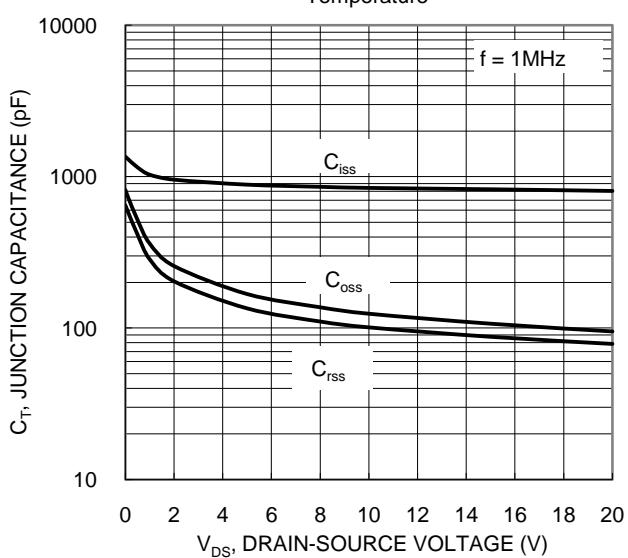
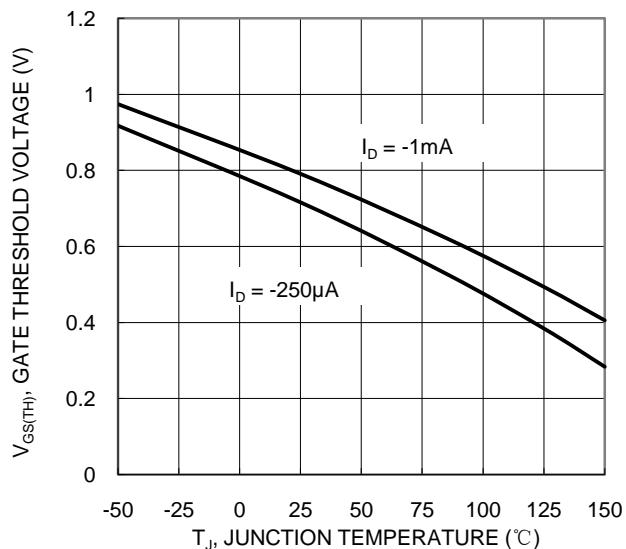
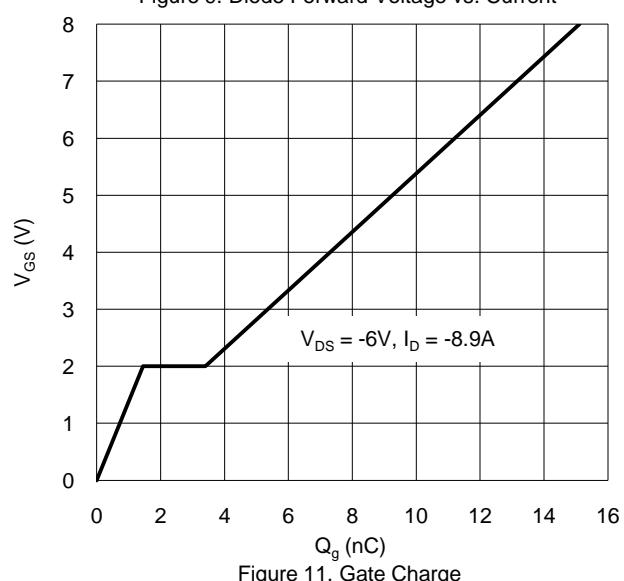
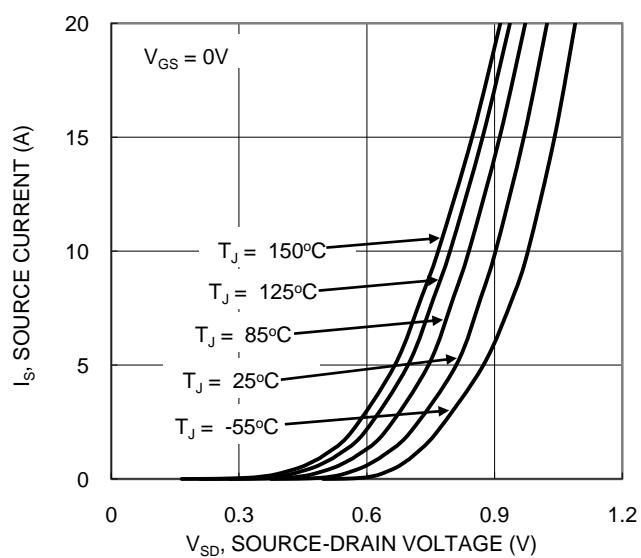
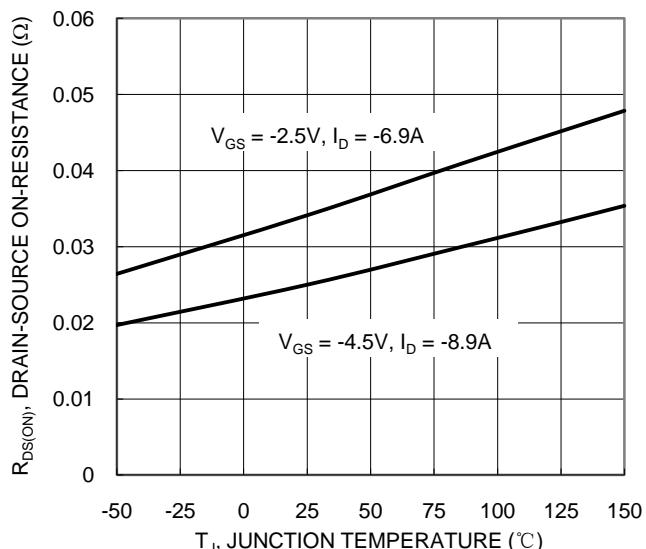


Figure 5. Typical On-Resistance vs Drain Current and Temperature





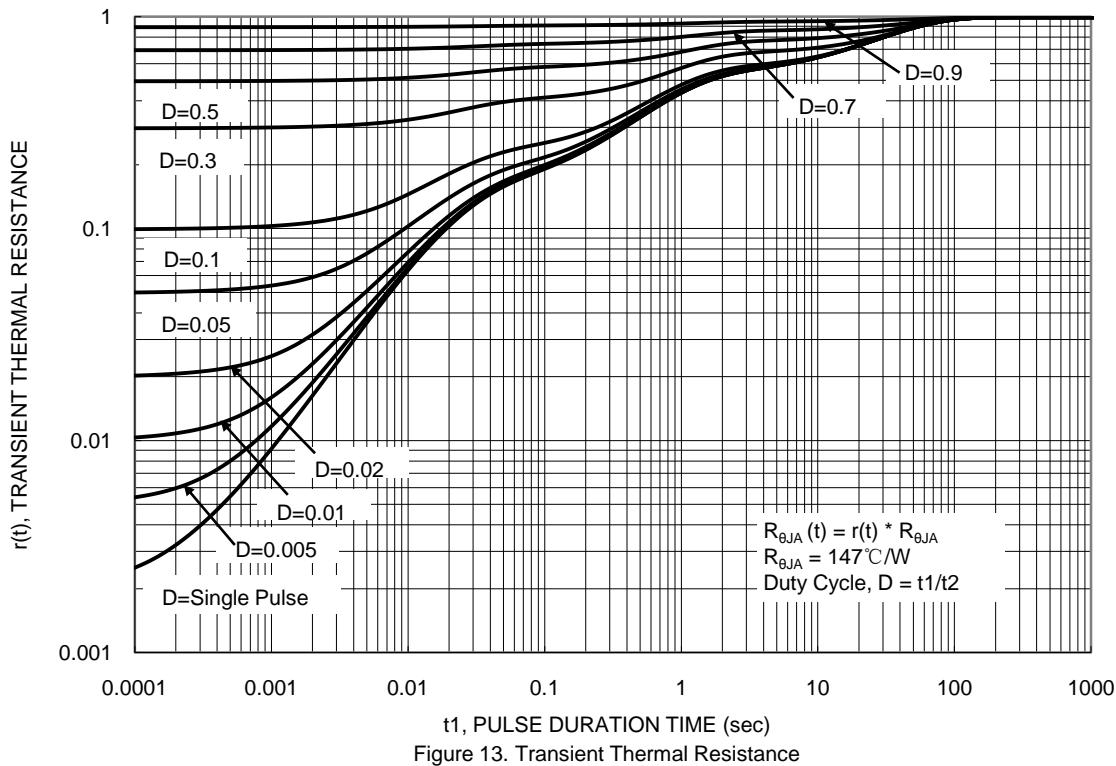
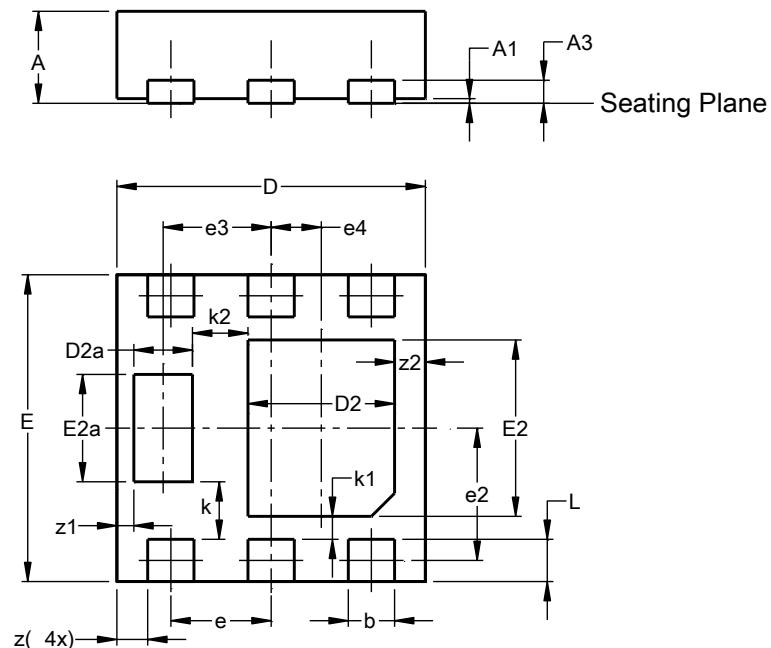


Figure 13. Transient Thermal Resistance

## Package Outline Dimension

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**U-DFN2020-6 (Type F)**



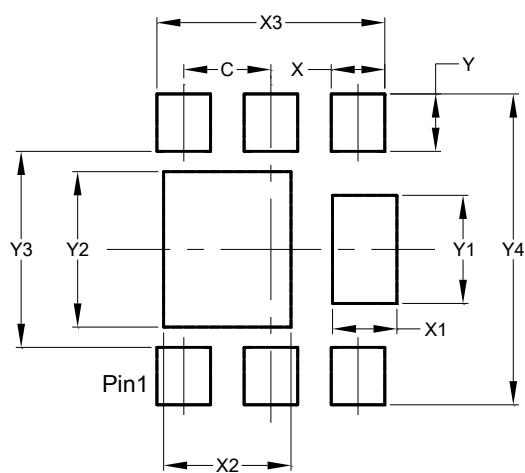
U-DFN2020-6 (Type F)			
Dim	Min	Max	Typ
<b>A</b>	0.57	0.63	0.60
<b>A1</b>	0.00	0.05	0.03
<b>A3</b>	-	-	0.15
<b>b</b>	0.25	0.35	0.30
<b>D</b>	1.95	2.05	2.00
<b>D2</b>	0.85	1.05	0.95
<b>D2a</b>	0.33	0.43	0.38
<b>E</b>	1.95	2.05	2.00
<b>E2</b>	1.05	1.25	1.15
<b>E2a</b>	0.65	0.75	0.70
<b>e</b>	0.65 BSC		
<b>e2</b>	0.863 BSC		
<b>e3</b>	0.70 BSC		
<b>e4</b>	0.325 BSC		
<b>k</b>	0.37 BSC		
<b>k1</b>	0.15 BSC		
<b>k2</b>	0.36 BSC		
<b>L</b>	0.225	0.325	0.275
<b>z</b>	0.20 BSC		
<b>z1</b>	0.110 BSC		
<b>z2</b>	0.20 BSC		

All Dimensions in mm

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**U-DFN2020-6 (Type F)**



Dimensions	Value (in mm)
<b>C</b>	0.650
<b>X</b>	0.400
<b>X1</b>	0.480
<b>X2</b>	0.950
<b>X3</b>	1.700
<b>Y</b>	0.425
<b>Y1</b>	0.800
<b>Y2</b>	1.150
<b>Y3</b>	1.450
<b>Y4</b>	2.300

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